

Abstract

Optoelectronic component having a heat sink

In the case of a radiation-emitting optoelectronic component (1) which is connected to a heat sink (3) and is intended for pulsed operation with the pulse duration  $D$ , and in which temperature changes of the optoelectronic component (1) take place with a thermal time constant  $\tau$  during pulsed operation, the thermal time constant  $\tau$  is matched to the pulse duration  $D$  in order to reduce the amplitude of the temperature changes. In a preferred manner, the thermal time constant  $\tau$  of the temperature changes of the optoelectronic component during pulsed operation is  $\tau \geq 0.5 D$ . The amplitude of the temperature changes during pulsed operation and associated fluctuating mechanical loads are thus advantageously reduced.

Figure 1